

128K SPI Bus Serial EEPROM

Device Selection Table

Part Number	Vcc Range	Page Size	Temp. Ranges	Packages
25LC128	2.5-5.5V	64 Byte	I, E	P, SM, SN, ST, MF
25AA128	1.8-5.5V	64 Byte	I	P, SM, SN, ST, MF

Features:

- Max. Clock 10 MHz
- Low-power CMOS Technology
 - Max. Write Current: 5 mA at 5.5V, 10 MHz
 - Read Current: 5 mA at 5.5V, 10 MHz
 - Standby Current: 5 μ A at 5.5V
- 16,384 x 8-bit Organization
- 64 Byte Page
- Self-timed Erase and Write Cycles (5 ms max.)
- Block Write Protection
 - Protect none, 1/4, 1/2 or all of array
- Built-in Write Protection
 - Power-on/off data protection circuitry
 - Write enable latch
 - Write-protect pin
- Sequential Read
- High Reliability
 - Endurance: 1,000,000 erase/write cycles
 - Data retention: > 200 years
 - ESD protection: > 4000V
- Temperature Ranges Supported;
 - Industrial (I): -40°C to +85°C
 - Automotive (E): -40°C to +125°C
- Pb-free and RoHS Compliant

Pin Function Table

Name	Function
$\overline{\text{CS}}$	Chip Select Input
SO	Serial Data Output
$\overline{\text{WP}}$	Write-Protect
Vss	Ground
SI	Serial Data Input
SCK	Serial Clock Input
HOLD	Hold Input
Vcc	Supply Voltage

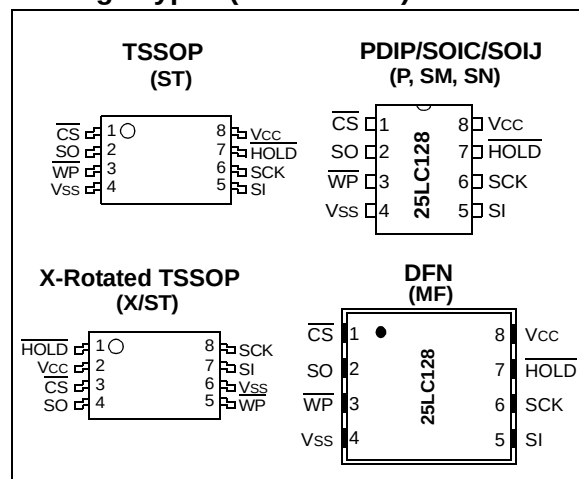
Description:

The Microchip Technology Inc. 25AA128/25LC128 (25XX128*) are 128k-bit Serial Electrically Erasable PROMs. The memory is accessed via a simple Serial Peripheral Interface (SPI) compatible serial bus. The bus signals required are a clock input (SCK) plus separate data in (SI) and data out (SO) lines. Access to the device is controlled through a Chip Select ($\overline{\text{CS}}$) input.

Communication to the device can be paused via the hold pin (HOLD). While the device is paused, transitions on its inputs will be ignored, with the exception of Chip Select, allowing the host to service higher priority interrupts.

The 25XX128 is available in standard packages including 8-lead PDIP, SOIJ and SOIC, and advanced packaging including 8-lead DFN and 8-lead TSSOP.

Package Types (not to scale)



* 25XX128 is used in this document as a generic part number for the 25AA128, 25LC128 devices.

25AA128/25LC128

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings ^(†)

V _{CC}	6.5V
All inputs and outputs w.r.t. V _{SS}	-0.6V to V _{CC} +1.0V
Storage temperature	-65°C to 150°C
Ambient temperature under bias	-40°C to 125°C
ESD protection on all pins	4 kV

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for an extended period of time may affect device reliability.

TABLE 1-1: DC CHARACTERISTICS

DC CHARACTERISTICS			Industrial (I): TA = -40°C to +85°C		V _{CC} = 1.8V to 5.5V	
			Automotive (E): TA = -40°C to +125°C		V _{CC} = 2.5V to 5.5V	
Param. No.	Sym.	Characteristic	Min.	Max.	Units	Test Conditions
D001	V _{IH1}	High-level input voltage	.7 V _{CC}	V _{CC} +1	V	
D002	V _{IL1}	Low-level input voltage	-0.3	0.3V _{CC}	V	V _{CC} ≥ 2.7V
D003	V _{IL2}		-0.3	0.2V _{CC}	V	V _{CC} < 2.7V
D004	V _{OL}	Low-level output voltage	—	0.4	V	I _{OL} = 2.1 mA
D005	V _{OL}		—	0.2	V	I _{OL} = 1.0 mA, V _{CC} < 2.5V
D006	V _{OH}	High-level output voltage	V _{CC} -0.5	—	V	I _{OH} = -400 μA
D007	I _{LI}	Input leakage current	—	±1	μA	$\overline{CS}$ = V _{CC} , V _{IN} = V _{SS} TO V _{CC}
D008	I _{LO}	Output leakage current	—	±1	μA	$\overline{CS}$ = V _{CC} , V _{OUT} = V _{SS} TO V _{CC}
D009	C _{INT}	Internal Capacitance (all inputs and outputs)	—	7	pF	TA = 25°C, CLK = 1.0 MHz, V _{CC} = 5.0V (Note)
D010	I _{CC} Read	Operating Current	—	5	mA	V _{CC} = 5.5V; F _{CLK} = 10.0 MHz; SO = Open
			—	2.5	mA	V _{CC} = 2.5V; F _{CLK} = 5.0 MHz; SO = Open
D011	I _{CC} Write	Standby Current	—	5	mA	V _{CC} = 5.5V
			—	3	mA	V _{CC} = 2.5V
D012	I _{CCS}	Standby Current	—	5	μA	$\overline{CS}$ = V _{CC} = 5.5V, Inputs tied to V _{CC} or V _{SS} , 125°C
			—	1	μA	$\overline{CS}$ = V _{CC} = 5.5V, Inputs tied to V _{CC} or V _{SS} , 85°C

Note: This parameter is periodically sampled and not 100% tested.

TABLE 1-2: AC CHARACTERISTICS

AC CHARACTERISTICS			Industrial (I): TA = -40°C to +85°C Automotive (E): TA = -40°C to +125°C			VCC = 1.8V to 5.5V VCC = 2.5V to 5.5V
Param. No.	Sym.	Characteristic	Min.	Max.	Units	Test Conditions
1	FCLK	Clock Frequency	— — —	10 5 3	MHz MHz MHz	4.5V ≤ VCC ≤ 5.5V 2.5V ≤ VCC < 4.5V 1.8V ≤ VCC < 2.5V
2	Tcss	$\overline{\text{CS}}$ Setup Time	50 100 150	— — —	ns ns ns	4.5V ≤ VCC ≤ 5.5V 2.5V ≤ VCC < 4.5V 1.8V ≤ VCC < 2.5V
3	TCSH	$\overline{\text{CS}}$ Hold Time	100 200 250	— — —	ns ns ns	4.5V ≤ VCC ≤ 5.5V 2.5V ≤ VCC < 4.5V 1.8V ≤ VCC < 2.5V
4	TcSD	$\overline{\text{CS}}$ Disable Time	50	—	ns	—
5	Tsu	Data Setup Time	10 20 30	— — —	ns ns ns	4.5V ≤ VCC ≤ 5.5V 2.5V ≤ VCC < 4.5V 1.8V ≤ VCC < 2.5V
6	THD	Data Hold Time	20 40 50	— — —	ns ns ns	4.5V ≤ VCC ≤ 5.5V 2.5V ≤ VCC < 4.5V 1.8V ≤ VCC < 2.5V
7	TR	CLK Rise Time	—	100	ns	(Note 1)
8	TF	CLK Fall Time	—	100	ns	(Note 1)
9	THI	Clock High Time	50 100 150	— — —	ns ns ns	4.5V ≤ VCC ≤ 5.5V 2.5V ≤ VCC < 4.5V 1.8V ≤ VCC < 2.5V
10	TLO	Clock Low Time	50 100 150	— — —	ns ns ns	4.5V ≤ VCC ≤ 5.5V 2.5V ≤ VCC < 4.5V 1.8V ≤ VCC < 2.5V
11	TCLD	Clock Delay Time	50	—	ns	—
12	TCLE	Clock Enable Time	50	—	ns	—
13	Tv	Output Valid from Clock Low	— — —	50 100 160	ns ns ns	4.5V ≤ VCC ≤ 5.5V 2.5V ≤ VCC < 4.5V 1.8V ≤ VCC < 2.5V
14	THO	Output Hold Time	0	—	ns	(Note 1)
15	Tdis	Output Disable Time	— — —	40 80 160	ns ns ns	4.5V ≤ VCC ≤ 5.5V(Note 1) 2.5V ≤ VCC < 4.5V(Note 1) 1.8V ≤ VCC < 2.5V(Note 1)
16	THS	$\overline{\text{HOLD}}$ Setup Time	20 40 80	— — —	ns ns ns	4.5V ≤ VCC ≤ 5.5V 2.5V ≤ VCC < 4.5V 1.8V ≤ VCC < 2.5V

Note 1: This parameter is periodically sampled and not 100% tested.

2: T_{wc} begins on the rising edge of $\overline{\text{CS}}$ after a valid write sequence and ends when the internal write cycle is complete.

3: This parameter is not tested but ensured by characterization. For endurance estimates in a specific application, please consult the Total Endurance™ Model which can be obtained from Microchip's web site: www.microchip.com.

25AA128/25LC128

TABLE 1-2: AC CHARACTERISTICS (CONTINUED)

AC CHARACTERISTICS			Industrial (I): TA = -40°C to +85°C Automotive (E): TA = -40°C to +125°C			VCC = 1.8V to 5.5V VCC = 2.5V to 5.5V
Param. No.	Sym.	Characteristic	Min.	Max.	Units	Test Conditions
17	THH	$\overline{\text{HOLD}}$ Hold Time	20 40 80	— — —	ns ns ns	4.5V ≤ VCC ≤ 5.5V 2.5V ≤ VCC < 4.5V 1.8V ≤ VCC < 2.5V
18	THZ	$\overline{\text{HOLD}}$ Low to Output High-Z	30 60 160	— — —	ns ns ns	4.5V ≤ VCC ≤ 5.5V(Note 1) 2.5V ≤ VCC < 4.5V(Note 1) 1.8V ≤ VCC < 2.5V(Note 1)
19	THV	$\overline{\text{HOLD}}$ High to Output Valid	30 60 160	— — —	ns ns ns	4.5V ≤ VCC ≤ 5.5V 2.5V ≤ VCC < 4.5V 1.8V ≤ VCC < 2.5V
20	Twc	Internal Write Cycle Time	—	5	ms	(NOTE 2)
21	—	Endurance	1,000,000	—	E/W Cycles	Page mode, 25°C, VCC = 5.5V (NOTE 3)

Note 1: This parameter is periodically sampled and not 100% tested.

2: Twc begins on the rising edge of $\overline{\text{CS}}$ after a valid write sequence and ends when the internal write cycle is complete.

3: This parameter is not tested but ensured by characterization. For endurance estimates in a specific application, please consult the Total Endurance™ Model which can be obtained from Microchip's web site: www.microchip.com.

TABLE 1-3: AC TEST CONDITIONS

AC Waveform:	
VLO = 0.2V	—
VHI = VCC - 0.2V	(Note 1)
VHI = 4.0V	(Note 2)
CL = 50 pF	—
Timing Measurement Reference Level	
Input	0.5 VCC
Output	0.5 VCC

Note 1: For VCC ≤ 4.0V

2: For VCC > 4.0V

FIGURE 1-1: HOLD TIMING

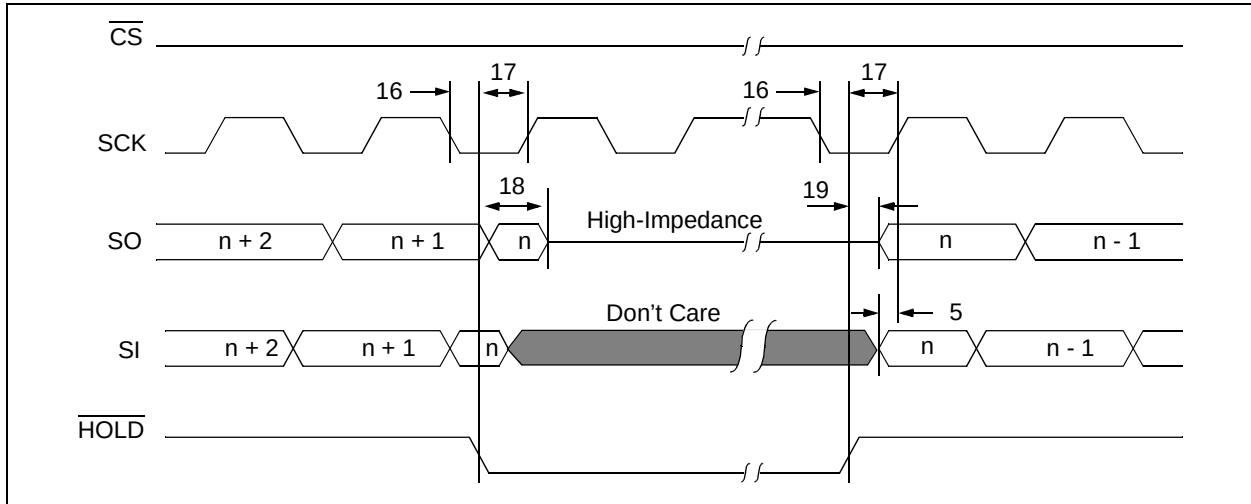


FIGURE 1-2: SERIAL INPUT TIMING

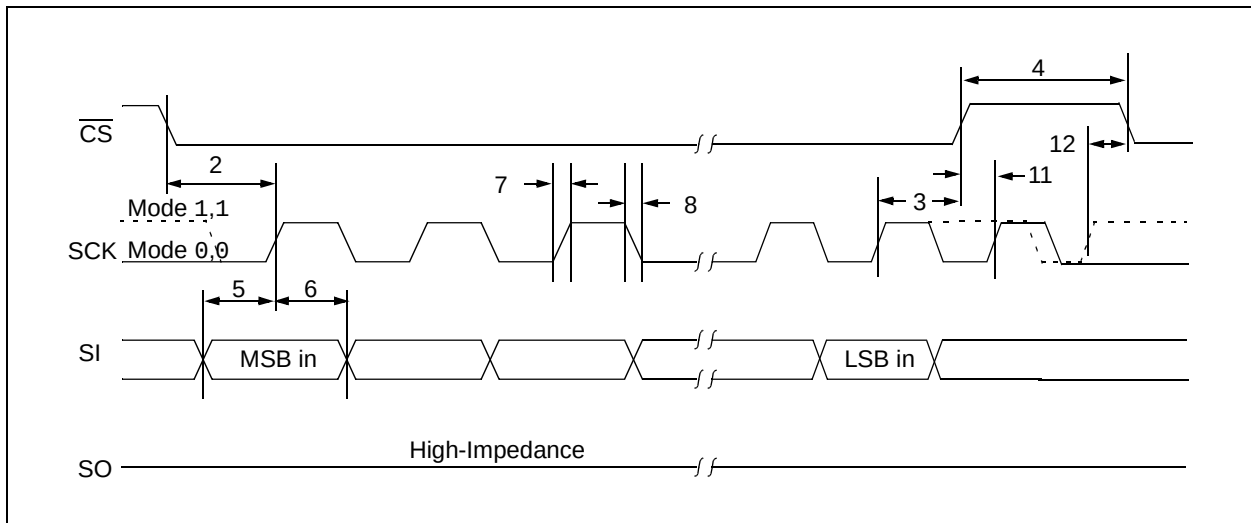
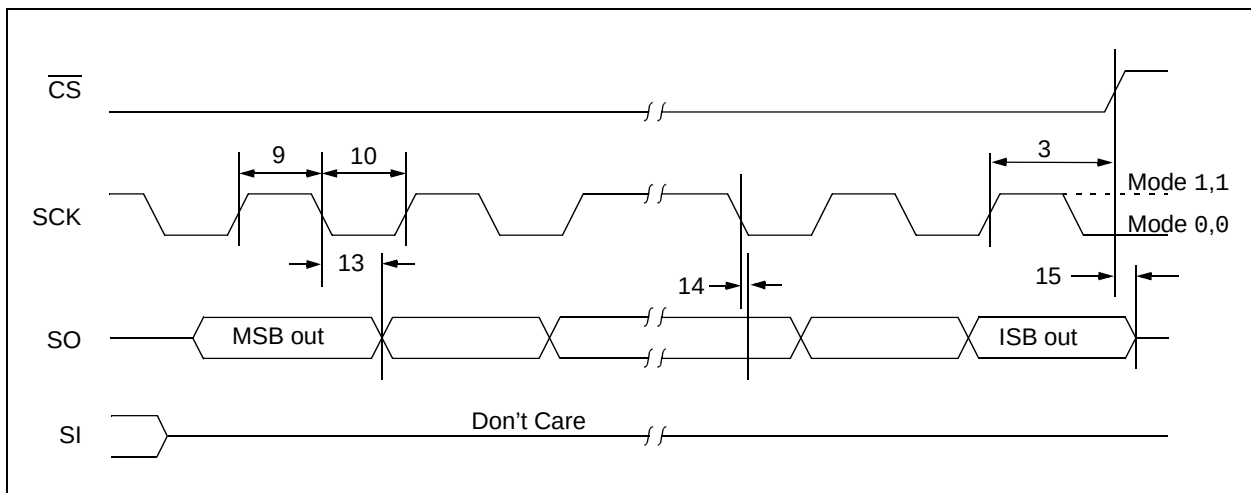


FIGURE 1-3: SERIAL OUTPUT TIMING



25AA128/25LC128

2.0 FUNCTIONAL DESCRIPTION

2.1 Principles of Operation

The 25XX128 is a 16,384 byte Serial EEPROM designed to interface directly with the Serial Peripheral Interface (SPI) port of many of today's popular microcontroller families, including Microchip's PIC® microcontrollers. It may also interface with microcontrollers that do not have a built-in SPI port by using discrete I/O lines programmed properly in firmware to match the SPI protocol.

The 25XX128 contains an 8-bit instruction register. The device is accessed via the SI pin, with data being clocked in on the rising edge of SCK. The $\overline{CS}$ pin must be low and the HOLD pin must be high for the entire operation.

Table 2-1 contains a list of the possible instruction bytes and format for device operation. All instructions, addresses and data are transferred MSB first, LSB last.

Data (SI) is sampled on the first rising edge of SCK after $\overline{CS}$ goes low. If the clock line is shared with other peripheral devices on the SPI bus, the user can assert the HOLD input and place the 25XX128 in 'HOLD' mode. After releasing the $\overline{HOLD}$ pin, operation will resume from the point when the HOLD was asserted.

2.2 Read Sequence

The device is selected by pulling $\overline{CS}$ low. The 8-bit READ instruction is transmitted to the 25XX128 followed by the 16-bit address, with two MSBs of the address being "don't care" bits. After the correct READ instruction and address are sent, the data stored in the memory at the selected address is shifted out on the SO pin. The data stored in the memory at the next address can be read sequentially by continuing to provide clock pulses. The internal Address Pointer is automatically incremented to the next higher address after each byte of data is shifted out. When the highest address is reached (3FFFh), the address counter rolls over to address 0000h, allowing the read cycle to be continued indefinitely. The read operation is terminated by raising the $\overline{CS}$ pin (Figure 2-1).

2.3 Write Sequence

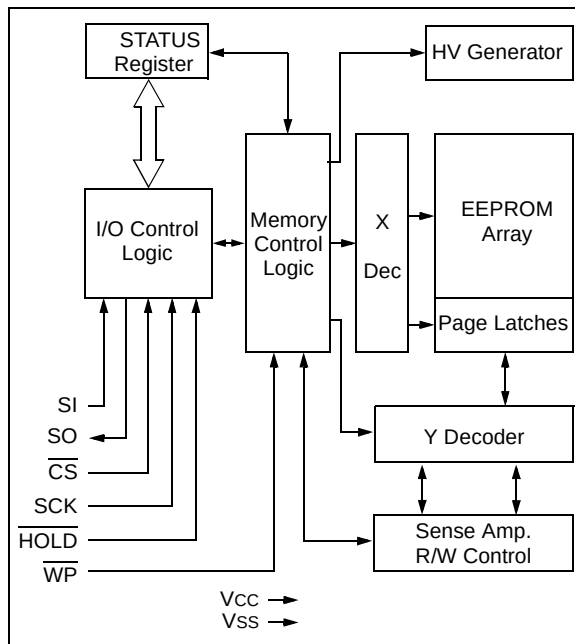
Prior to any attempt to write data to the 25XX128, the write enable latch must be set by issuing the $\overline{WREN}$ instruction (Figure 2-4). This is done by setting $\overline{CS}$ low and then clocking out the proper instruction into the 25XX128. After all eight bits of the instruction are transmitted, the $\overline{CS}$ must be brought high to set the write enable latch. If the write operation is initiated immediately after the $\overline{WREN}$ instruction without $\overline{CS}$ being brought high, the data will not be written to the array because the write enable latch will not have been properly set.

Once the write enable latch is set, the user may proceed by setting the $\overline{CS}$ low, issuing a $\overline{WRITE}$ instruction, followed by the 16-bit address, with two MSBs of the address being "don't care" bits, and then the data to be written. Up to 64 bytes of data can be sent to the device before a write cycle is necessary. The only restriction is that all of the bytes must reside in the same page.

Note: Page write operations are limited to writing bytes within a single physical page, **regardless** of the number of bytes actually being written. Physical page boundaries start at addresses that are integer multiples of the page buffer size (or 'page size') and, end at addresses that are integer multiples of page size – 1. If a Page Write command attempts to write across a physical page boundary, the result is that the data wraps around to the beginning of the current page (overwriting data previously stored there), instead of being written to the next page as might be expected. It is therefore necessary for the application software to prevent page write operations that would attempt to cross a page boundary.

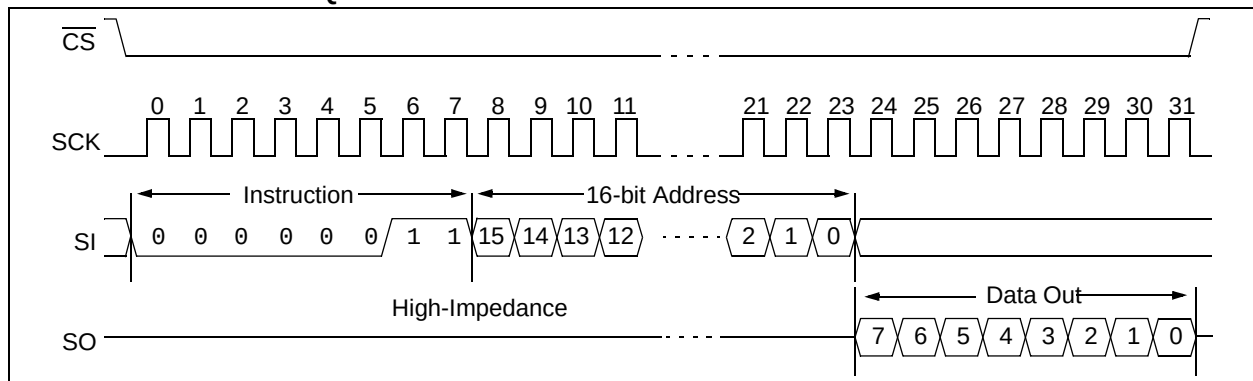
For the data to be actually written to the array, the $\overline{CS}$ must be brought high after the Least Significant bit (D0) of the n^{th} data byte has been clocked in. If $\overline{CS}$ is brought high at any other time, the write operation will not be completed. Refer to Figure 2-2 and Figure 2-3 for more detailed illustrations on the byte write sequence and the page write sequence respectively. While the write is in progress, the STATUS register may be read to check the status of the WPEN, WIP, WEL, BP1 and BP0 bits (Figure 2-6). A read attempt of a memory array location will not be possible during a write cycle. When the write cycle is completed, the write enable latch is reset.

BLOCK DIAGRAM

**TABLE 2-1: INSTRUCTION SET**

Instruction Name	Instruction Format	Description
READ	0000 0011	Read data from memory array beginning at selected address
WRITE	0000 0010	Write data to memory array beginning at selected address
WRDI	0000 0100	Reset the write enable latch (disable write operations)
WREN	0000 0110	Set the write enable latch (enable write operations)
RDSR	0000 0101	Read STATUS register
WRSR	0000 0001	Write STATUS register

FIGURE 2-1: READ SEQUENCE



25AA128/25LC128

FIGURE 2-2: BYTE WRITE SEQUENCE

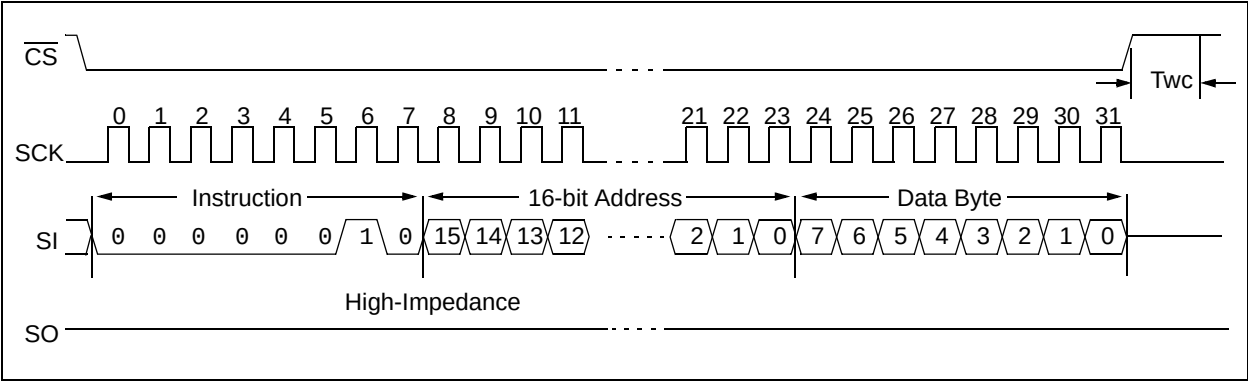
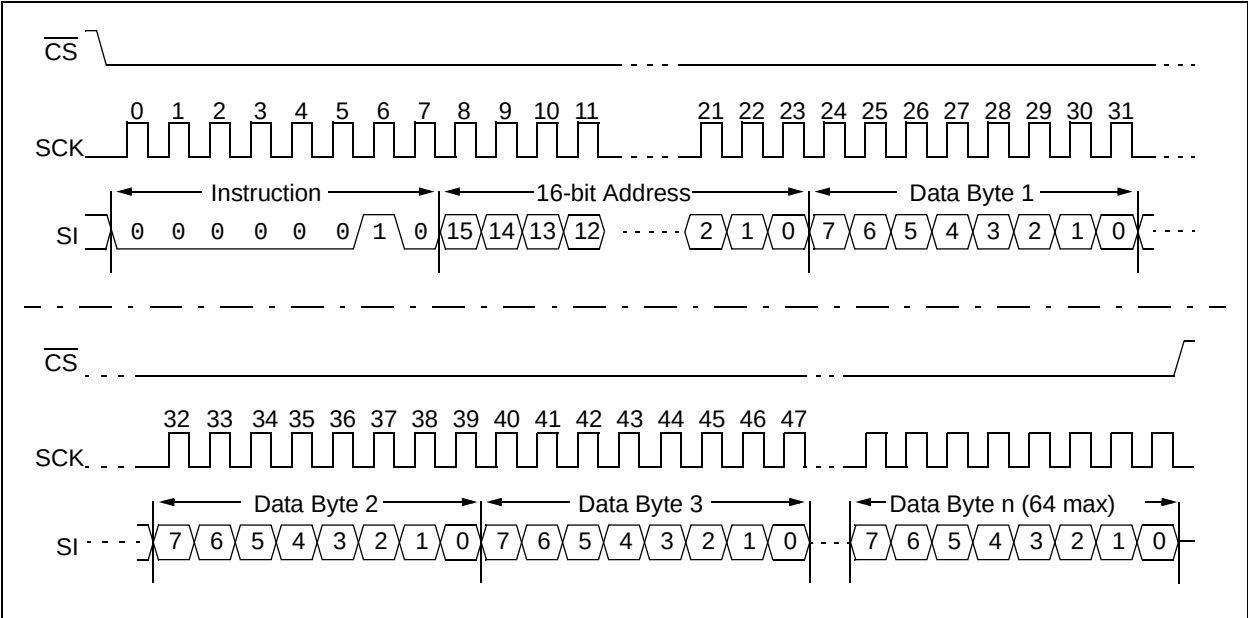


FIGURE 2-3: PAGE WRITE SEQUENCE



2.4 Write Enable (WREN) and Write Disable (WRDI)

The 25XX128 contains a write enable latch. See Table 2-4 for the write-protect functionality matrix. This latch must be set before any write operation will be completed internally. The WREN instruction will set the latch, and the WRDI will reset the latch.

The following is a list of conditions under which the write enable latch will be reset:

- Power-up
- WRDI instruction successfully executed
- WRSR instruction successfully executed
- WRITE instruction successfully executed

FIGURE 2-4: WRITE ENABLE SEQUENCE (WREN)

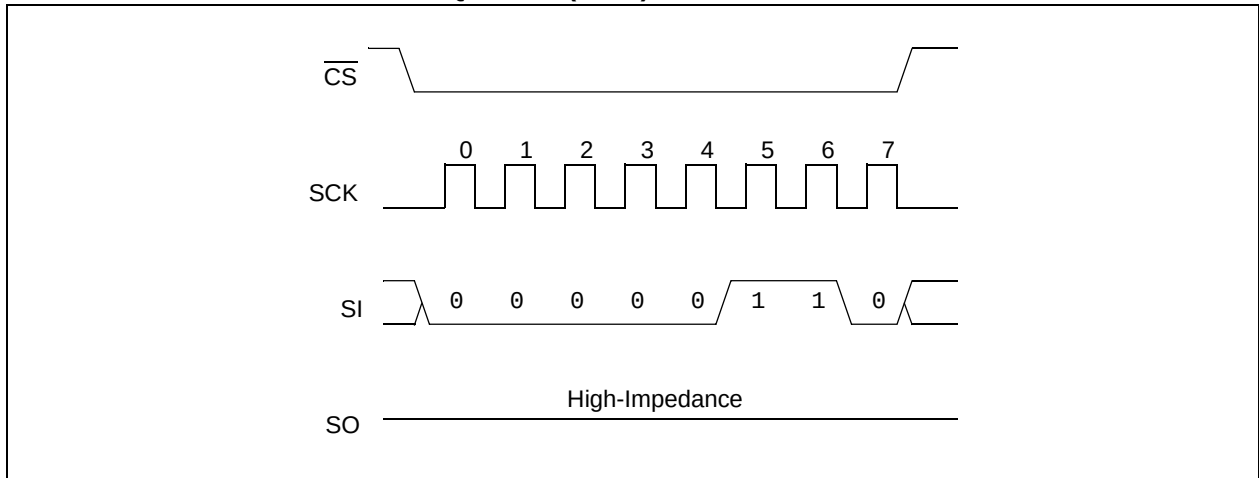
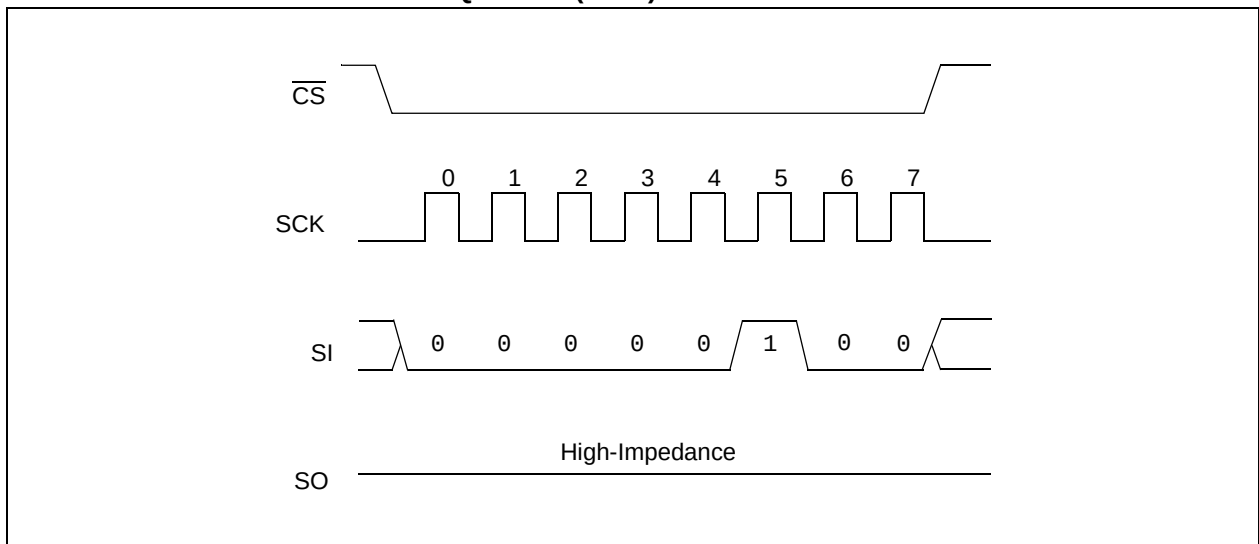


FIGURE 2-5: WRITE DISABLE SEQUENCE (WRDI)



25AA128/25LC128

2.5 Read Status Register Instruction (RDSR)

The Read Status Register instruction (RDSR) provides access to the STATUS register. The STATUS register may be read at any time, even during a write cycle. The STATUS register is formatted as follows:

TABLE 2-2: STATUS REGISTER

7	6	5	4	3	2	1	0
W/R	–	–	–	W/R	W/R	R	R
WPEN	X	X	X	BP1	BP0	WEL	WIP
W/R = writable/readable. R = read-only.							

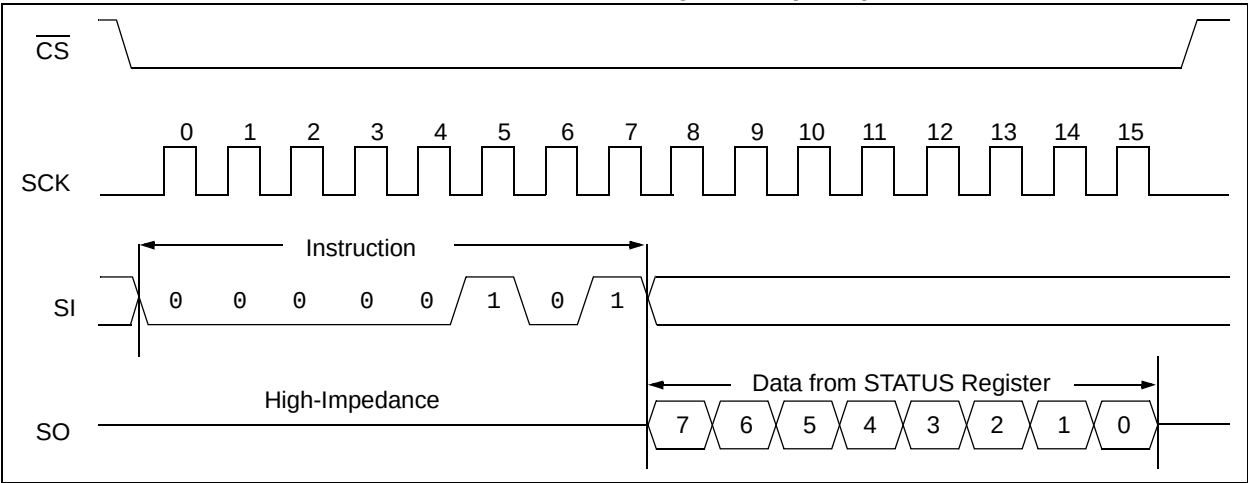
The **Write-In-Process (WIP)** bit indicates whether the 25XX128 is busy with a write operation. When set to a '1', a write is in progress, when set to a '0', no write is in progress. This bit is read-only.

The **Write Enable Latch (WEL)** bit indicates the status of the write enable latch and is read-only. When set to a '1', the latch allows writes to the array, when set to a '0', the latch prohibits writes to the array. The state of this bit can always be updated via the WREN or WRDI commands regardless of the state of write protection on the STATUS register. These commands are shown in Figure 2-4 and Figure 2-5.

The **Block Protection (BP0 and BP1)** bits indicate which blocks are currently write-protected. These bits are set by the user issuing the WRSR instruction. These bits are nonvolatile, and are shown in Table 2-3.

See Figure 2-6 for the RDSR timing sequence.

FIGURE 2-6: READ STATUS REGISTER TIMING SEQUENCE (RDSR)



2.6 Write Status Register (WRSR)

The Write Status Register (WRSR) instruction allows the user to write to the nonvolatile bits in the STATUS register as shown in Table 2-2. The user is able to select one of four levels of protection for the array by writing to the appropriate bits in the STATUS register. The array is divided up into four segments. The user has the ability to write-protect none, one, two, or all four of the segments of the array. The partitioning is controlled as shown in Table 2-3.

The Write-Protect Enable (WPEN) bit is a nonvolatile bit that is available as an enable bit for the $\overline{WP}$ pin. The Write-Protect ($\overline{WP}$) pin and the Write-Protect Enable (WPEN) bit in the STATUS register control the programmable hardware write-protect feature. Hardware write protection is enabled when $\overline{WP}$ pin is low and the WPEN bit is high. Hardware write protection is disabled when either the $\overline{WP}$ pin is high or the WPEN bit is low. When the chip is hardware write-protected,

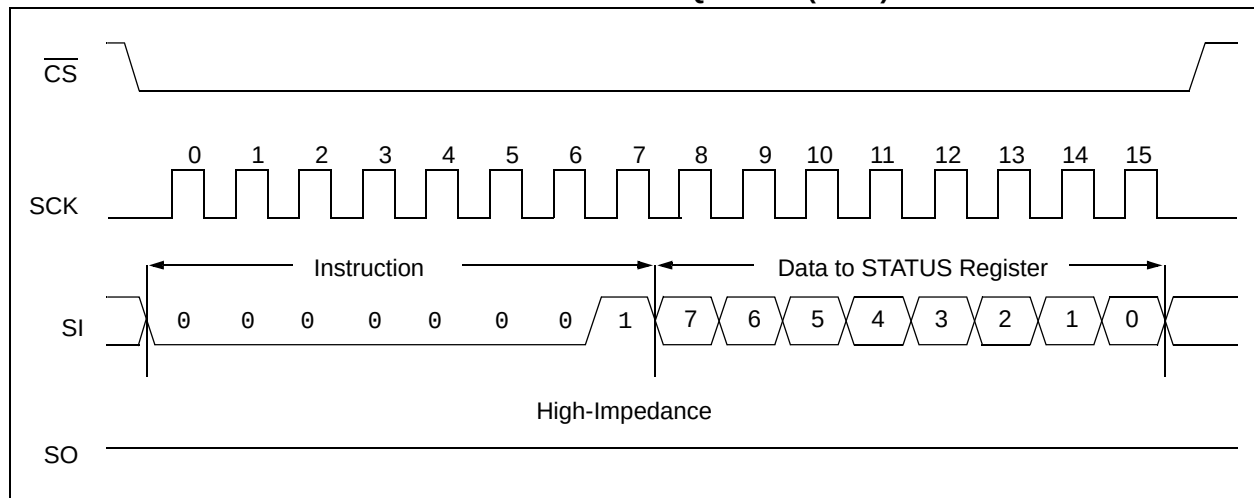
only writes to nonvolatile bits in the STATUS register are disabled. See Table 2-4 for a matrix of functionality on the WPEN bit.

See Figure 2-7 for the WRSR timing sequence.

TABLE 2-3: ARRAY PROTECTION

BP1	BP0	Array Addresses Write-Protected
0	0	none
0	1	upper 1/4 (3000h-3FFFh)
1	0	upper 1/2 (2000h-3FFFh)
1	1	all (0000h-3FFFh)

FIGURE 2-7: WRITE STATUS REGISTER TIMING SEQUENCE (WRSR)



Note: An internal write cycle (T_{wc}) is initiated on the rising edge of $\overline{CS}$ after a valid write STATUS register

25AA128/25LC128

2.7 Data Protection

The following protection has been implemented to prevent inadvertent writes to the array:

- The write enable latch is reset on power-up
- A write enable instruction must be issued to set the write enable latch
- After a byte write, page write or STATUS register write, the write enable latch is reset
- $\overline{CS}$ must be set high after the proper number of clock cycles to start an internal write cycle
- Access to the array during an internal write cycle is ignored and programming is continued

2.8 Power-On State

The 25XX128 powers on in the following state:

- The device is in low-power Standby mode ($\overline{CS} = 1$)
- The write enable latch is reset
- SO is in high-impedance state
- A high-to-low-level transition on $\overline{CS}$ is required to enter active state

TABLE 2-4: WRITE-PROTECT FUNCTIONALITY MATRIX

WEL (SR bit 1)	WPEN (SR bit 7)	$\overline{WP}$ (pin 3)	Protected Blocks	Unprotected Blocks	STATUS Register
0	x	x	Protected	Protected	Protected
1	0	x	Protected	Writable	Writable
1	1	0 (low)	Protected	Writable	Protected
1	1	1 (high)	Protected	Writable	Writable

x = don't care

3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE

Name	Pin Number	X-Rotated Pin Number	Function
$\overline{\text{CS}}$	1	3	Chip Select Input
SO	2	4	Serial Data Output
$\overline{\text{WP}}$	3	5	Write-Protect Pin
VSS	4	6	Ground
SI	5	7	Serial Data Input
SCK	6	8	Serial Clock Input
$\overline{\text{HOLD}}$	7	1	Hold Input
VCC	8	2	Supply Voltage

Note: The exposed pad on the DFN package can be connected to VSS or left floating.

3.1 Chip Select ($\overline{\text{CS}}$)

A low level on this pin selects the device. A high level deselects the device and forces it into Standby mode. However, a programming cycle which is already initiated or in progress will be completed, regardless of the $\overline{\text{CS}}$ input signal. If $\overline{\text{CS}}$ is brought high during a program cycle, the device will go into Standby mode as soon as the programming cycle is complete. When the device is deselected, SO goes to the high-impedance state, allowing multiple parts to share the same SPI bus. A low-to-high transition on $\overline{\text{CS}}$ after a valid write sequence initiates an internal write cycle. After power-up, a low level on $\overline{\text{CS}}$ is required prior to any sequence being initiated.

3.2 Serial Output (SO)

The SO pin is used to transfer data out of the 25XX128. During a read cycle, data is shifted out on this pin after the falling edge of the serial clock.

3.3 Write-Protect ($\overline{\text{WP}}$)

This pin is used in conjunction with the WPEN bit in the STATUS register to prohibit writes to the nonvolatile bits in the STATUS register. When $\overline{\text{WP}}$ is low and WPEN is high, writing to the nonvolatile bits in the STATUS register is disabled. All other operations function normally. When $\overline{\text{WP}}$ is high, all functions, including writes to the nonvolatile bits in the STATUS register, operate normally. If the WPEN bit is set, $\overline{\text{WP}}$ low during a STATUS register write sequence will disable writing to the STATUS register. If an internal write cycle has already begun, $\overline{\text{WP}}$ going low will have no effect on the write.

The $\overline{\text{WP}}$ pin function is blocked when the WPEN bit in the STATUS register is low. This allows the user to install the 25XX128 in a system with $\overline{\text{WP}}$ pin grounded and still be able to write to the STATUS register. The WP pin functions will be enabled when the WPEN bit is set high.

3.4 Serial Input (SI)

The SI pin is used to transfer data into the device. It receives instructions, addresses and data. Data is latched on the rising edge of the serial clock.

3.5 Serial Clock (SCK)

The SCK is used to synchronize the communication between a master and the 25XX128. Instructions, addresses or data present on the SI pin are latched on the rising edge of the clock input, while data on the SO pin is updated after the falling edge of the clock input.

3.6 Hold ($\overline{\text{HOLD}}$)

The $\overline{\text{HOLD}}$ pin is used to suspend transmission to the 25XX128 while in the middle of a serial sequence without having to retransmit the entire sequence again. It must be held high any time this function is not being used. Once the device is selected and a serial sequence is underway, the $\overline{\text{HOLD}}$ pin may be pulled low to pause further serial communication without resetting the serial sequence. The $\overline{\text{HOLD}}$ pin must be brought low while SCK is low, otherwise the HOLD function will not be invoked until the next SCK high-to-low transition. The 25XX128 must remain selected during this sequence. The SI, SCK and SO pins are in a high-impedance state during the time the device is paused and transitions on these pins will be ignored. To resume serial communication, $\overline{\text{HOLD}}$ must be brought high while the SCK pin is low, otherwise serial communication will not resume. Lowering the $\overline{\text{HOLD}}$ line at any time will tri-state the SO line.

25AA128/25LC128

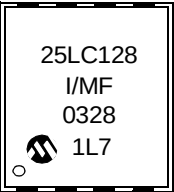
4.0 PACKAGING INFORMATION

4.1 Package Marking Information

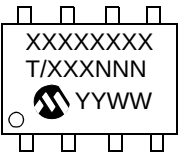
8-Lead DFN



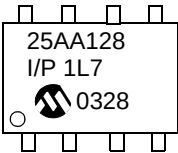
Example:



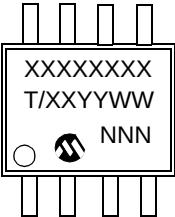
8-Lead PDIP



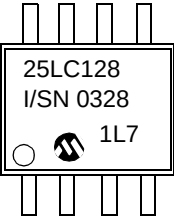
Example:



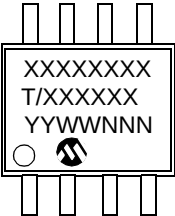
8-Lead SOIC



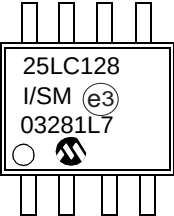
Example:



8-Lead SOIJ



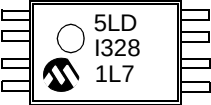
Example:



8-Lead TSSOP



Example:



TSSOP 1st Line Marking	
Device	std mark
25AA128	5AD
25AA128X	5ADX
25LC128	5LD
25LC128X	5LDX

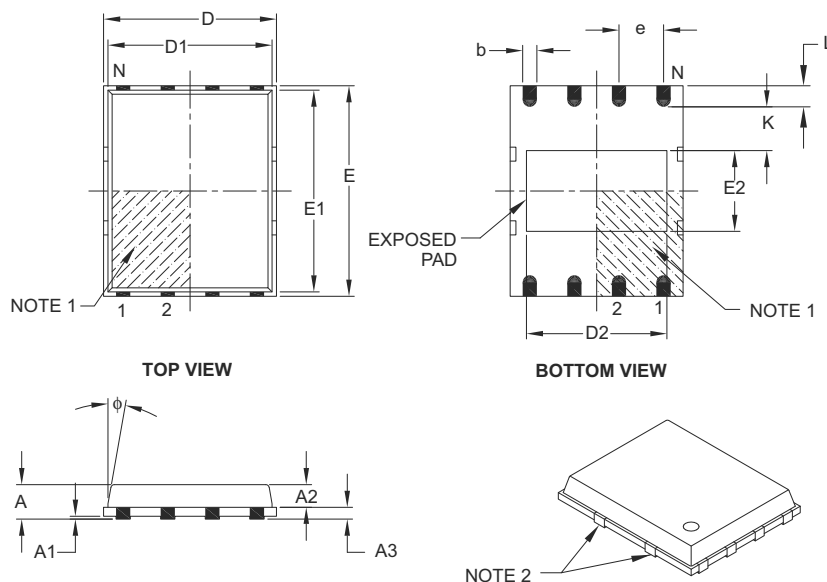
Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

25AA128/25LC128

8-Lead Plastic Dual Flat, No Lead Package (MF) – 6x5 mm Body [DFN-S] PUNCH SINGULATED

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	1.27 BSC		
Overall Height	A	–	0.85	1.00
Molded Package Thickness	A2	–	0.65	0.80
Standoff	A1	0.00	0.01	0.05
Base Thickness	A3	0.20 REF		
Overall Length	D	4.92 BSC		
Molded Package Length	D1	4.67 BSC		
Exposed Pad Length	D2	3.85	4.00	4.15
Overall Width	E	5.99 BSC		
Molded Package Width	E1	5.74 BSC		
Exposed Pad Width	E2	2.16	2.31	2.46
Contact Width	b	0.35	0.40	0.47
Contact Length	L	0.50	0.60	0.75
Contact-to-Exposed Pad	K	0.20	–	–
Model Draft Angle Top	ϕ	–	–	12°

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package may have one or more exposed tie bars at ends.
- Dimensioning and tolerancing per ASME Y14.5M.

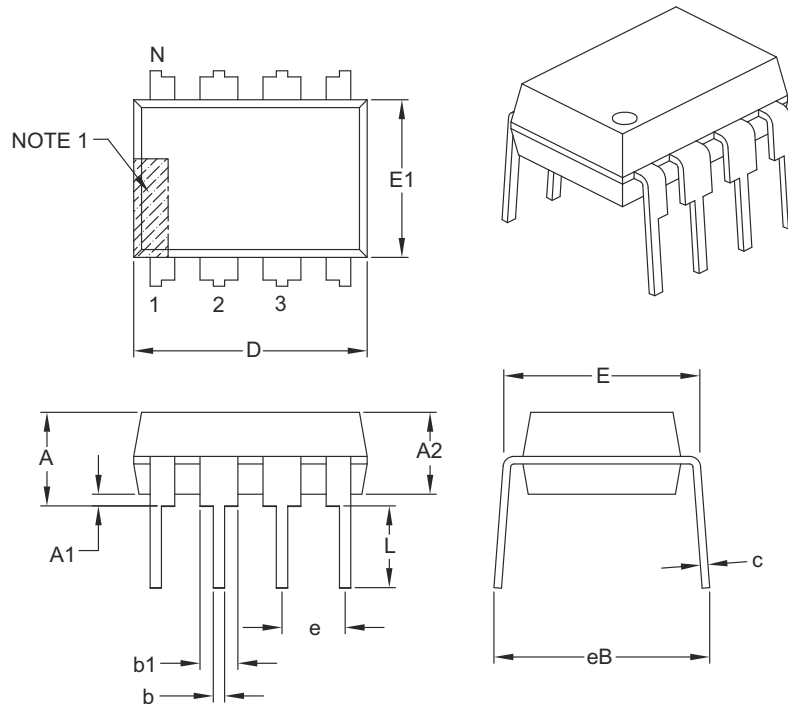
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-113B

8-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	.100 BSC		
Top to Seating Plane	A	–	–	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.348	.365	.400
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

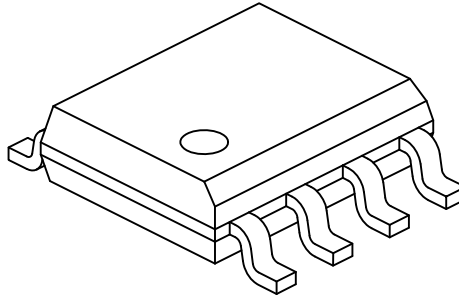
- Pin 1 visual index feature may vary, but must be located with the hatched area.
- § Significant Characteristic.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-018B

8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	1.27 BSC		
Overall Height	A	-	-	1.75
Molded Package Thickness	A2	1.25	-	-
Standoff §	A1	0.10	-	0.25
Overall Width	E	6.00 BSC		
Molded Package Width	E1	3.90 BSC		
Overall Length	D	4.90 BSC		
Chamfer (Optional)	h	0.25	-	0.50
Foot Length	L	0.40	-	1.27
Footprint	L1	1.04 REF		
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.17	-	0.25
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

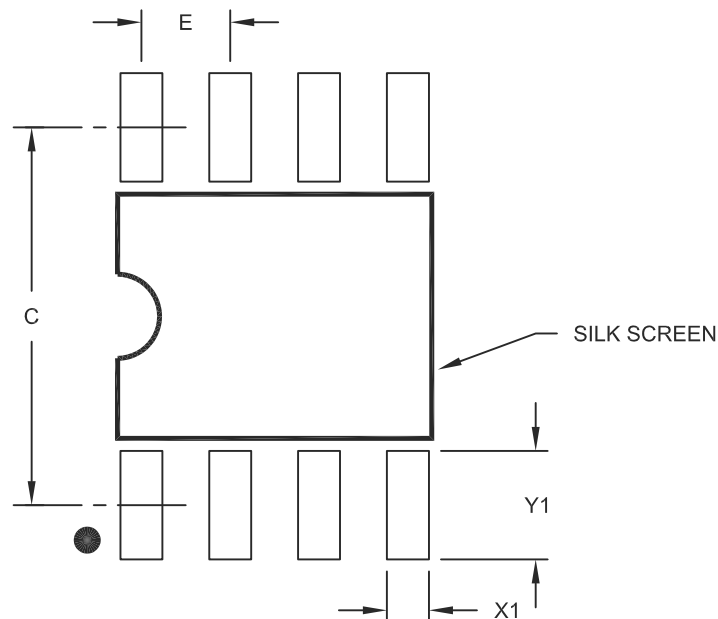
- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing No. C04-057C Sheet 2 of 2

25AA128/25LC128

8-Lead Plastic Small Outline (SN) – Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		5.40	
Contact Pad Width (X8)	X1			0.60
Contact Pad Length (X8)	Y1			1.55

Notes:

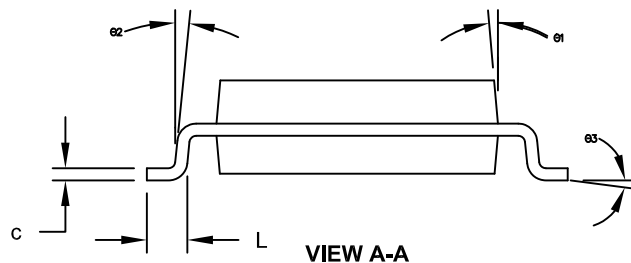
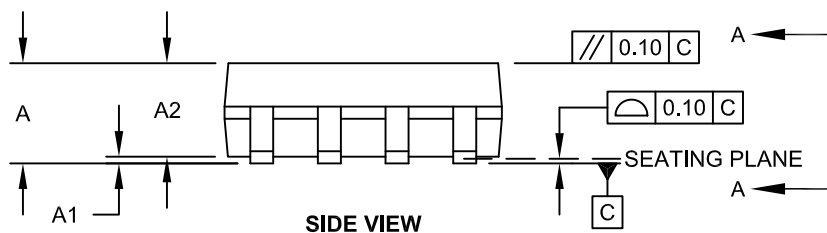
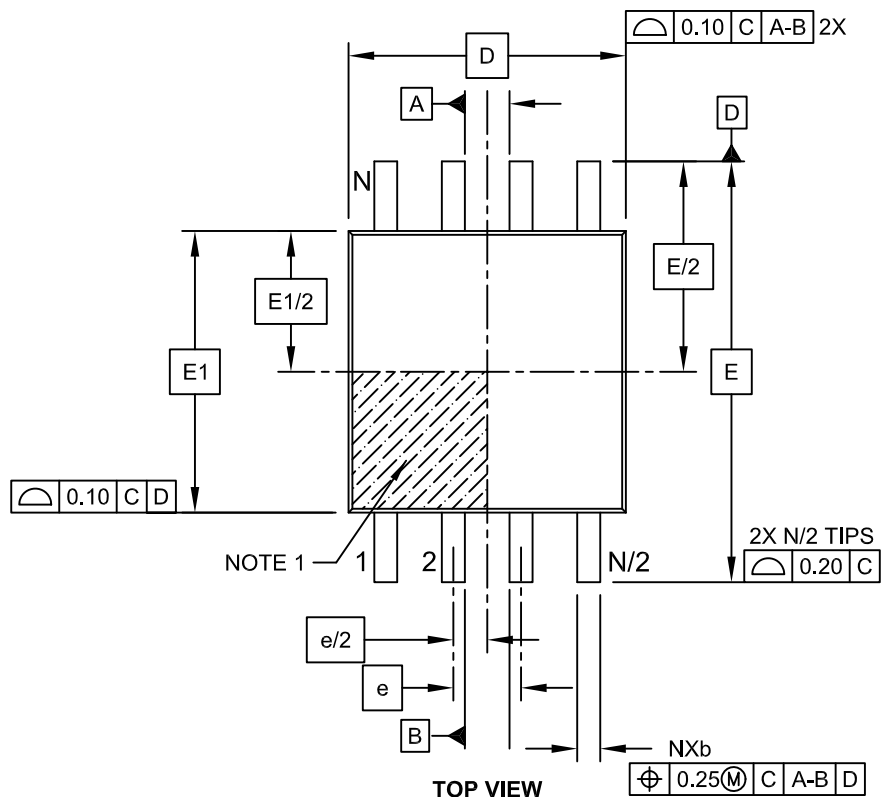
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2057A

8-Lead Plastic Small Outline (SM) - Medium, 5.28 mm Body [SOIJ]

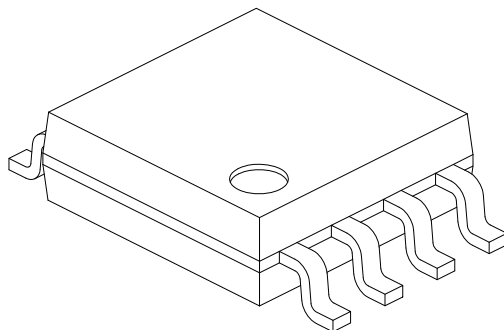
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



25AA128/25LC128

8-Lead Plastic Small Outline (SM) - Medium, 5.28 mm Body [SOIJ]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	1.27 BSC		
Overall Height	A	1.77	-	2.03
Standoff §	A1	0.05		0.25
Molded Package Thickness	A2	1.75	-	1.98
Overall Width	E	7.94 BSC		
Molded Package Width	E1	5.25 BSC		
Overall Length	D	5.26 BSC		
Foot Length	L	0.51	-	0.76
Lead Thickness	c	0.15	-	0.25
Lead Width	b	0.36	-	0.51
Mold Draft Angle	Ø1	-	-	15°
Lead Angle	Ø2	0°	-	8°
Foot Angle	Ø3	0°	-	8°

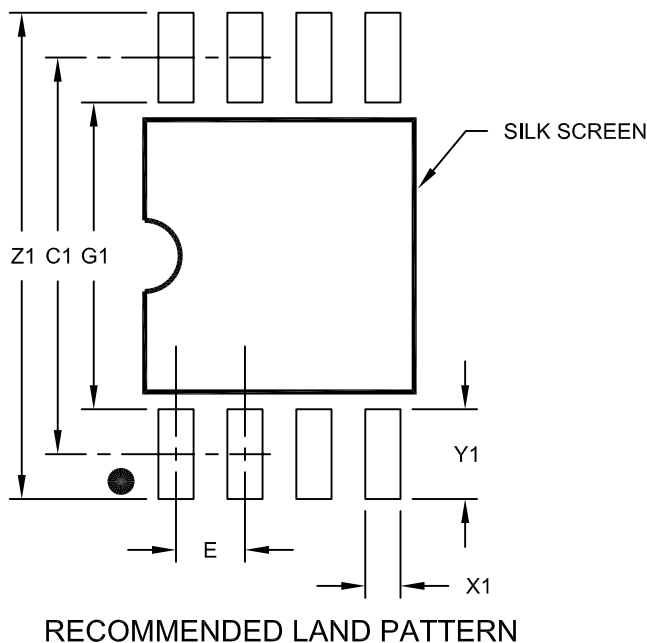
Notes:

1. SOIJ, JEITA/EIAJ Standard, Formerly called SOIC
2. § Significant Characteristic
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25mm per side.

Microchip Technology Drawing No. C04-056C Sheet 2 of 2

8-Lead Plastic Small Outline (SM) - Medium, 5.28 mm Body [SOIJ]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Overall Width	Z1			9.00
Contact Pad Spacing	C1		7.30	
Contact Pad Width (X8)	X1			0.65
Contact Pad Length (X8)	Y1			1.70
Distance Between Pads	G1	5.60		
Distance Between Pads	G	0.62		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

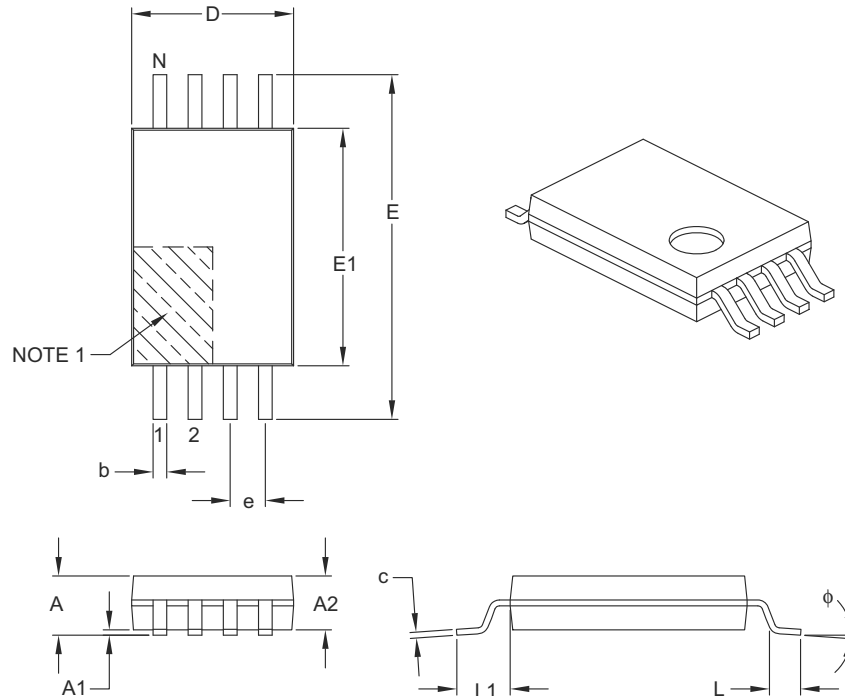
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2056C

25AA128/25LC128

8-Lead Plastic Thin Shrink Small Outline (ST) – 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packages>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	0.65 BSC		
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.80	1.00	1.05
Standoff	A1	0.05	–	0.15
Overall Width	E	6.40 BSC		
Molded Package Width	E1	4.30	4.40	4.50
Molded Package Length	D	2.90	3.00	3.10
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	φ	0°	–	8°
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.19	–	0.30

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

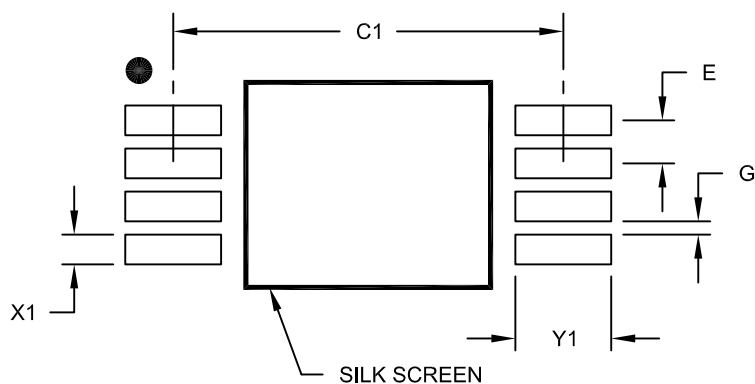
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-086B

8-Lead Plastic Thin Shrink Small Outline (ST) - 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C1		5.90	
Contact Pad Width (X8)	X1			0.45
Contact Pad Length (X8)	Y1			1.45
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension, Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2086A

25AA128/25LC128

APPENDIX A: REVISION HISTORY

Revision A(9/03)

Original Release

Revision B (12/03)

Corrections to Section 1.0, Electrical Characteristics.

Revision C (5/07)

Removed Preliminary status; Revised Table 1-2, Para. 7 and 8; Revised Table 1-3, CL; Revised trademarks; Replaced Package drawings (Rev. AP); Replaced On-Line Support; Revised Product ID section.

Revision D (06/09)

Added X-Rotated TSSOP to package types; Revised Table 1-2, Param. 21; Revised Table 3-1; Revised TSSOP Line Marking table; Added SOIC Land Pattern; Revised Product ID section.

Revision E (7/2011)

Added SOIJ (SM) package.

THE MICROCHIP WEB SITE

Microchip provides online support via our WWW site at www.microchip.com. This web site is used as a means to make files and information easily available to customers. Accessible by using your favorite Internet browser, the web site contains the following information:

- **Product Support** – Data sheets and errata, application notes and sample programs, design resources, user's guides and hardware support documents, latest software releases and archived software
- **General Technical Support** – Frequently Asked Questions (FAQ), technical support requests, online discussion groups, Microchip consultant program member listing
- **Business of Microchip** – Product selector and ordering guides, latest Microchip press releases, listing of seminars and events, listings of Microchip sales offices, distributors and factory representatives

CUSTOMER CHANGE NOTIFICATION SERVICE

Microchip's customer notification service helps keep customers current on Microchip products. Subscribers will receive e-mail notification whenever there are changes, updates, revisions or errata related to a specified product family or development tool of interest.

To register, access the Microchip web site at www.microchip.com. Under "Support", click on "Customer Change Notification" and follow the registration instructions.

CUSTOMER SUPPORT

Users of Microchip products can receive assistance through several channels:

- Distributor or Representative
- Local Sales Office
- Field Application Engineer (FAE)
- Technical Support
- Development Systems Information Line

Customers should contact their distributor, representative or field application engineer (FAE) for support. Local sales offices are also available to help customers. A listing of sales offices and locations is included in the back of this document.

Technical support is available through the web site at: <http://microchip.com/support>

25AA128/25LC128

READER RESPONSE

It is our intention to provide you with the best documentation possible to ensure successful use of your Microchip product. If you wish to provide your comments on organization, clarity, subject matter, and ways in which our documentation can better serve you, please FAX your comments to the Technical Publications Manager at (480) 792-4150.

Please list the following information, and use this outline to provide us with your comments about this document.

TO: Technical Publications Manager Total Pages Sent _____

RE: Reader Response

From: Name _____

Company _____

Address _____

City / State / ZIP / Country _____

Telephone: (____) _____ - _____ FAX: (____) _____ - _____

Application (optional):

Would you like a reply? ___Y___N

Device: 25AA128/25LC128

Literature Number: DS21831E

Questions:

1. What are the best features of this document?

2. How does this document meet your hardware and software development needs?

3. Do you find the organization of this document easy to follow? If not, why?

4. What additions to the document do you think would enhance the structure and subject?

5. What deletions from the document could be made without affecting the overall usefulness?

6. Is there any incorrect or misleading information (what and where)?

7. How would you improve this document?

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>		<u>X</u>	-	<u>X</u>	<u>/XX</u>
Device		Tape & Reel		Temp Range	Package
Device:	25AA128 =	128k-bit, 1.8V, 64-Byte Page, SPI Serial EEPROM			
	25LC128 =	128k-bit, 2.5V, 64-Byte Page, SPI Serial EEPROM			
	25AA128X =	128k-bit, 1.8V, 64-Byte Page, SPI Serial EEPROM in alternate pinout (ST only)			
	25LC128X =	128k-bit, 2.5V, 64-Byte Page, SPI Serial EEPROM in alternate pinout (ST only)			
Tape & Reel:	Blank =	Standard packaging (tube)			
	T =	Tape & Reel			
Temperature Range:	I =	-40°C to+85°C			
	E =	-40°C to+125°C			
Package:	MF =	Micro Lead Frame (6 x 5 mm body), 8-lead			
	P =	Plastic DIP (300 mil body), 8-lead			
	SN =	Plastic SOIC (3.90 mm body), 8-lead			
	SM =	Plastic SOIJ (5.28 mm body), 8-lead			
	ST =	TSSOP, 8-lead			

Examples:

- a) 25AA128T-I/SN = 128k-bit, 1.8V Serial EEPROM, Industrial temp., Tape & Reel, SOIC package
- b) 25AA128T-I/ST = 128k-bit, 1.8V Serial EEPROM, Industrial temp., Tape & Reel, TSSOP package
- c) 25LC128-I/P = 128k-bit, 2.5V Serial EEPROM, Industrial temp., P-DIP package
- d) 25LC128T-E/MF = 128k-bit, 2.5V Serial EEPROM, Extended temp., Tape & Reel, DFN package
- e) 25LC128XT-I/ST = 128k-bit, 2.5V Serial EEPROM, Industrial temp., Tape & Reel, Rotated pinout, TSSOP package

25AA128/25LC128

NOTES:

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

Trademarks

The Microchip name and logo, the Microchip logo, dsPIC, KEELOQ, KEELOQ logo, MPLAB, PIC, PICmicro, PICSTART, PIC³² logo, rfPIC and UNI/O are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

FilterLab, Hampshire, HI-TECH C, Linear Active Thermistor, MXDEV, MXLAB, SEEVAL and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Analog-for-the-Digital Age, Application Maestro, chipKIT, chipKIT logo, CodeGuard, dsPICDEM, dsPICDEM.net, dsPICworks, dsSPEAK, ECAN, ECONOMONITOR, FanSense, HI-TIDE, In-Circuit Serial Programming, ICSP, Mindi, MiWi, MPASM, MPLAB Certified logo, MPLIB, MPLINK, mTouch, Omniscent Code Generation, PICC, PICC-18, PICDEM, PICDEM.net, PICKit, PICtail, REAL ICE, rfLAB, Select Mode, Total Endurance, TSHARC, UniWinDriver, WiperLock and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2003-2011, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

 Printed on recycled paper.

ISBN: 978-1-61341-354-8

QUALITY MANAGEMENT SYSTEM
CERTIFIED BY DNV
== ISO/TS 16949:2009 ==

Microchip received ISO/TS-16949:2002 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.

Worldwide Sales and Service

AMERICAS

Corporate Office
 2355 West Chandler Blvd.
 Chandler, AZ 85224-6199
 Tel: 480-792-7200
 Fax: 480-792-7277
 Technical Support:
<http://www.microchip.com/support>
 Web Address:
www.microchip.com

Atlanta
 Duluth, GA
 Tel: 678-957-9614
 Fax: 678-957-1455

Boston
 Westborough, MA
 Tel: 774-760-0087
 Fax: 774-760-0088

Chicago
 Itasca, IL
 Tel: 630-285-0071
 Fax: 630-285-0075

Cleveland
 Independence, OH
 Tel: 216-447-0464
 Fax: 216-447-0643

Dallas
 Addison, TX
 Tel: 972-818-7423
 Fax: 972-818-2924

Detroit
 Farmington Hills, MI
 Tel: 248-538-2250
 Fax: 248-538-2260

Indianapolis
 Noblesville, IN
 Tel: 317-773-8323
 Fax: 317-773-5453

Los Angeles
 Mission Viejo, CA
 Tel: 949-462-9523
 Fax: 949-462-9608

Santa Clara
 Santa Clara, CA
 Tel: 408-961-6444
 Fax: 408-961-6445

Toronto
 Mississauga, Ontario,
 Canada
 Tel: 905-673-0699
 Fax: 905-673-6509

ASIA/PACIFIC

Asia Pacific Office
 Suites 3707-14, 37th Floor
 Tower 6, The Gateway
 Harbour City, Kowloon
 Hong Kong
 Tel: 852-2401-1200
 Fax: 852-2401-3431

Australia - Sydney
 Tel: 61-2-9868-6733
 Fax: 61-2-9868-6755

China - Beijing
 Tel: 86-10-8569-7000
 Fax: 86-10-8528-2104

China - Chengdu
 Tel: 86-28-8665-5511
 Fax: 86-28-8665-7889

China - Chongqing
 Tel: 86-23-8980-9588
 Fax: 86-23-8980-9500

China - Hangzhou
 Tel: 86-571-2819-3180
 Fax: 86-571-2819-3189

China - Hong Kong SAR
 Tel: 852-2401-1200
 Fax: 852-2401-3431

China - Nanjing
 Tel: 86-25-8473-2460
 Fax: 86-25-8473-2470

China - Qingdao
 Tel: 86-532-8502-7355
 Fax: 86-532-8502-7205

China - Shanghai
 Tel: 86-21-5407-5533
 Fax: 86-21-5407-5066

China - Shenyang
 Tel: 86-24-2334-2829
 Fax: 86-24-2334-2393

China - Shenzhen
 Tel: 86-755-8203-2660
 Fax: 86-755-8203-1760

China - Wuhan
 Tel: 86-27-5980-5300
 Fax: 86-27-5980-5118

China - Xian
 Tel: 86-29-8833-7252
 Fax: 86-29-8833-7256

China - Xiamen
 Tel: 86-592-2388138
 Fax: 86-592-2388130

China - Zhuhai
 Tel: 86-756-3210040
 Fax: 86-756-3210049

ASIA/PACIFIC

India - Bangalore
 Tel: 91-80-3090-4444
 Fax: 91-80-3090-4123

India - New Delhi
 Tel: 91-11-4160-8631
 Fax: 91-11-4160-8632

India - Pune
 Tel: 91-20-2566-1512
 Fax: 91-20-2566-1513

Japan - Yokohama
 Tel: 81-45-471- 6166
 Fax: 81-45-471-6122

Korea - Daegu
 Tel: 82-53-744-4301
 Fax: 82-53-744-4302

Korea - Seoul
 Tel: 82-2-554-7200
 Fax: 82-2-558-5932 or
 82-2-558-5934

Malaysia - Kuala Lumpur
 Tel: 60-3-6201-9857
 Fax: 60-3-6201-9859

Malaysia - Penang
 Tel: 60-4-227-8870
 Fax: 60-4-227-4068

Philippines - Manila
 Tel: 63-2-634-9065
 Fax: 63-2-634-9069

Singapore
 Tel: 65-6334-8870
 Fax: 65-6334-8850

Taiwan - Hsin Chu
 Tel: 886-3-6578-300
 Fax: 886-3-6578-370

Taiwan - Kaohsiung
 Tel: 886-7-213-7830
 Fax: 886-7-330-9305

Taiwan - Taipei
 Tel: 886-2-2500-6610
 Fax: 886-2-2508-0102

Thailand - Bangkok
 Tel: 66-2-694-1351
 Fax: 66-2-694-1350

EUROPE

Austria - Wels
 Tel: 43-7242-2244-39
 Fax: 43-7242-2244-393

Denmark - Copenhagen
 Tel: 45-4450-2828
 Fax: 45-4485-2829

France - Paris
 Tel: 33-1-69-53-63-20
 Fax: 33-1-69-30-90-79

Germany - Munich
 Tel: 49-89-627-144-0
 Fax: 49-89-627-144-44

Italy - Milan
 Tel: 39-0331-742611
 Fax: 39-0331-466781

Netherlands - Drunen
 Tel: 31-416-690399
 Fax: 31-416-690340

Spain - Madrid
 Tel: 34-91-708-08-90
 Fax: 34-91-708-08-91

UK - Wokingham
 Tel: 44-118-921-5869
 Fax: 44-118-921-5820

05/02/11

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9